

### Scope

This specification is applied to Multicomp thermoelectric modules Revision of these specifications is carried out after consent

## **Specifications**

Para	Remarks		
Internal resistance	0.41 Ω	Note-1	
I max.	8.5	Note-2	
V max.	3.8	Note-3	
-	Th = 25°C	-	-
Q max.	19 W	-	Note-4
ΔT max.	70°C	-	Note-5
Solder melting point	232	Note-6	
Maximum compress	1 M	Note-7	

Note-1: Measured by AC 4 - terminal method at 25°C

Note-2 : Maximum current at  $\Delta T$  max. Note-3 : Maximum voltage at  $\Delta T$  max.

Note-4: Maximum cooling capacity at I max. V max. and  $\Delta T = 0$ °C

Note-5: Maximum temperature difference at I max. V max. and Q = 0 W

(Maximum parameters are measured in a vacuum 1.3 P) Note-6: The solder melting point of thermoelectric module

Note-7: Recommended maximum compression (not destruction limit)

#### **Recommendations:**

Maximum temperature for short time: 200°C

Operation temperature up to 150°C for long lifetime;

ON / OFF cycling mode reliability at high temperature

Recommended operation current not higher than 0.7 of I max.

Preferable application; thermal management

E modules are epoxy sealed for moisture protection

#### **Specification Table** Thot = 27°C

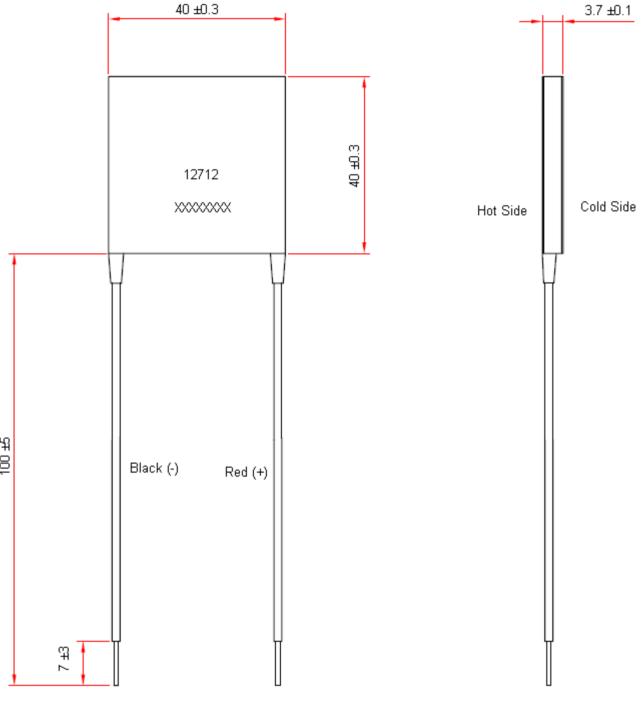
I max. (A)	U max. (V)	Qc max. W	dT max. °C	Α	В	Н	Part Number
8.5	3.8	19	70	20	20	3.8	MCPF-031-14-11

Dimensions : Millimetres





## **Outline Drawing**

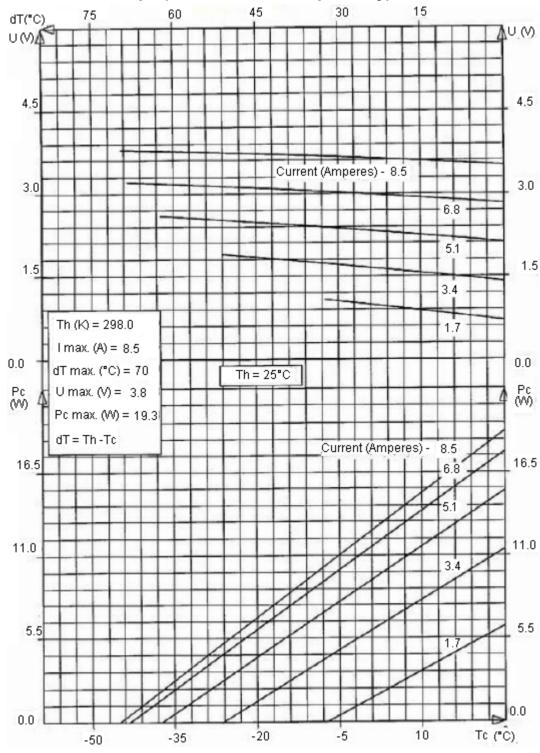


Dimensions : Millimetres



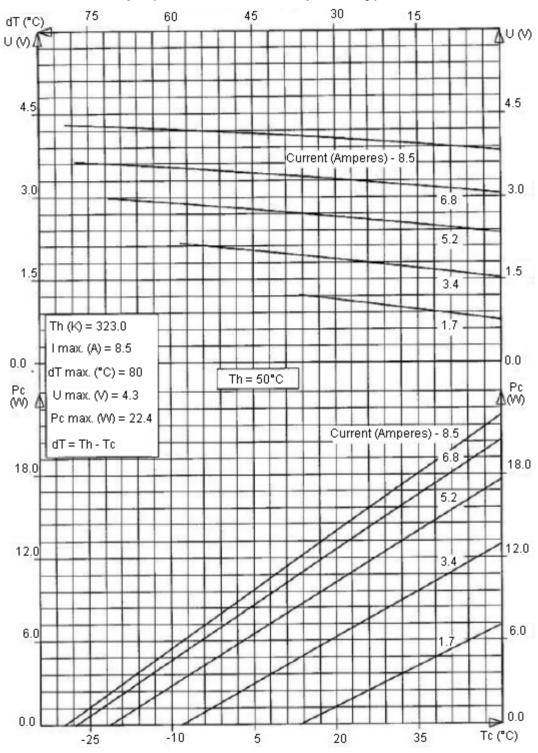


## Performance Graph (298K and 323K Respectively)





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